

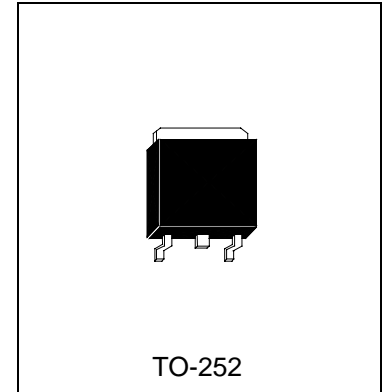


# HJ772

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HJ772 is designed for using in output stage of 20 W audio amplifier, voltage regulator, DC-DC converter and relay driver.



## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
  - Storage Temperature ..... -55 ~ +150 °C
  - Junction Temperature ..... +150 °C
- Maximum Power Dissipation
  - Total Power Dissipation (Tc=25°C) ..... 10 W
- Maximum Voltages and Currents
  - BVCBO Collector to Base Voltage ..... -40 V
  - BVCEO Collector to Emitter Voltage ..... -30 V
  - BVEBO Emitter to Base Voltage ..... -5 V
  - IC Collector Current (DC) ..... -3 A
  - IC Collector Current (Pulse) ..... -7 A
  - IB Base Current (DC) ..... -600 mA

## Thermal Characteristic

Characteristic	Symbol	Max.	Unit
Thermal Resistance, junction to case	Rθjc	12.5	°C/W

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA, IE=0
BVCEO	-30	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-1	uA	VCB=-30V, IE=0
IEBO	-	-	-1	uA	VEB=-3V, IC=0
*VCE(sat)	-	-0.3	-0.5	V	IC=-2A, IB=-0.2A
*VBE(sat)	-	-1	-2	V	IC=-2A, IB=-0.2A
*hFE1	30	-	-		VCE=-2V, IC=-20mA
*hFE2	100	-	500		VCE=-2V, IC=-1A
fT	-	80	-	MHz	VCE=-5V, IC=-0.1A, f=100MHz
Cob	-	55	-	pF	VCB=-10V, f=-1MHz, IE=0

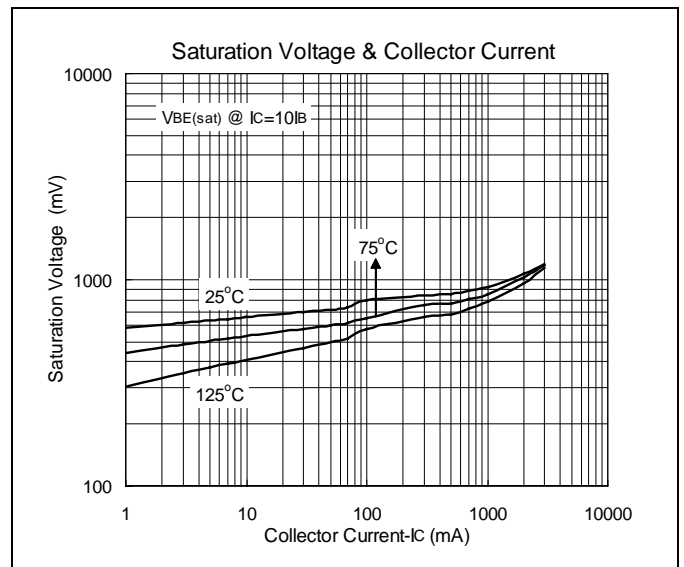
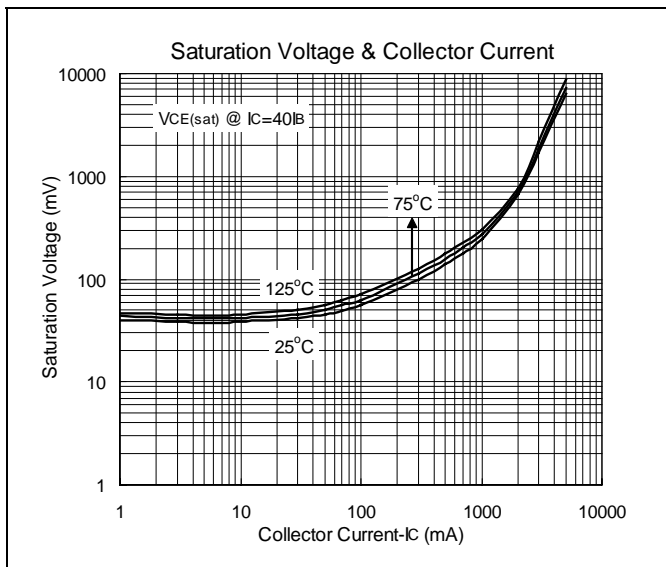
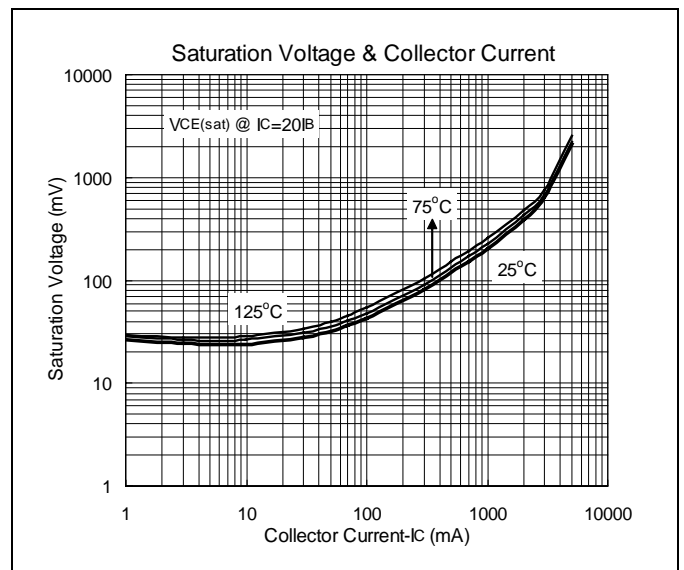
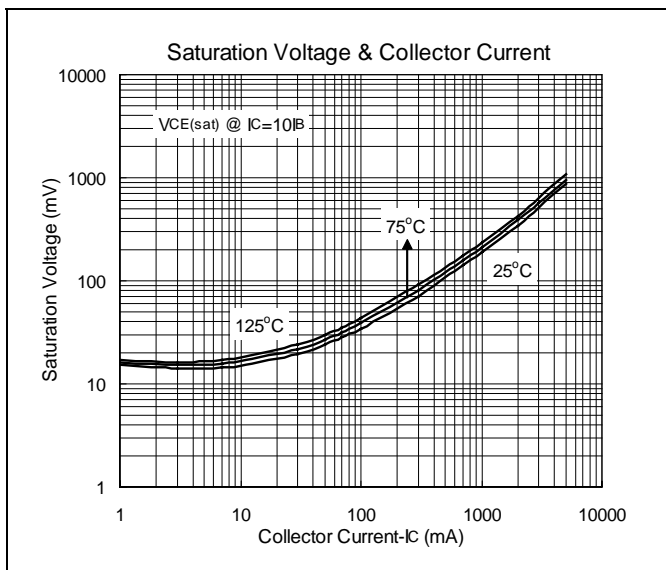
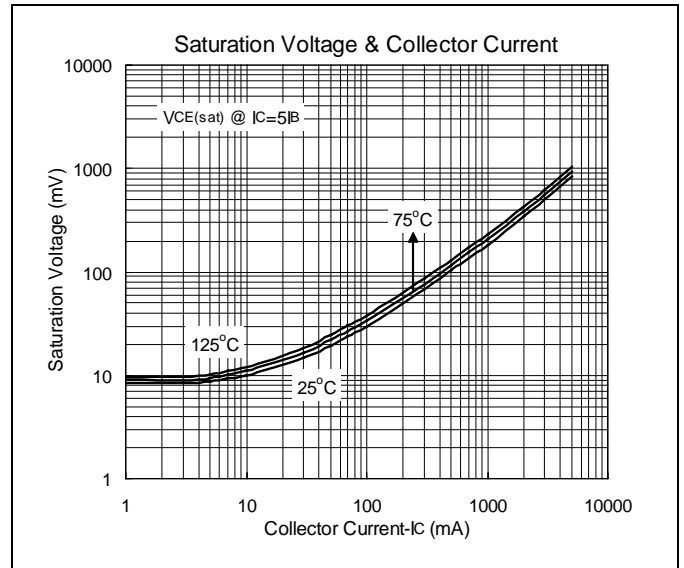
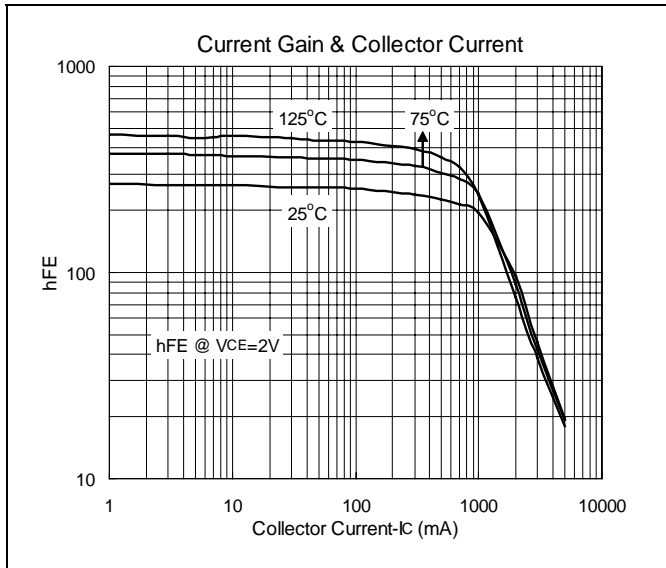
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

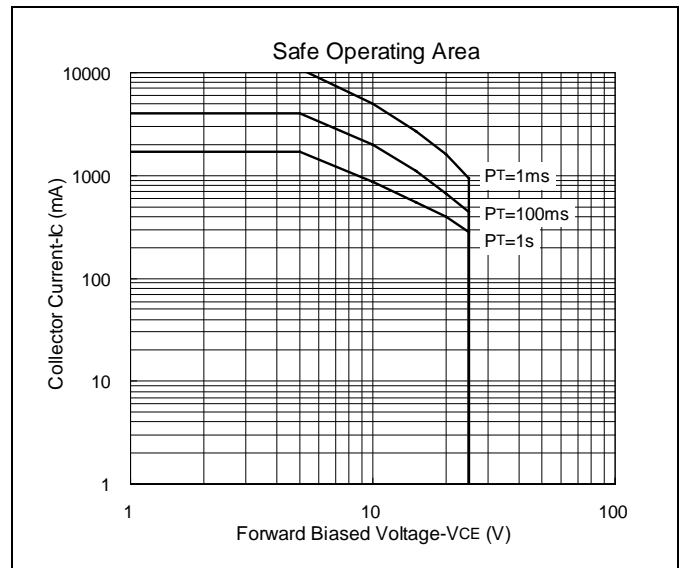
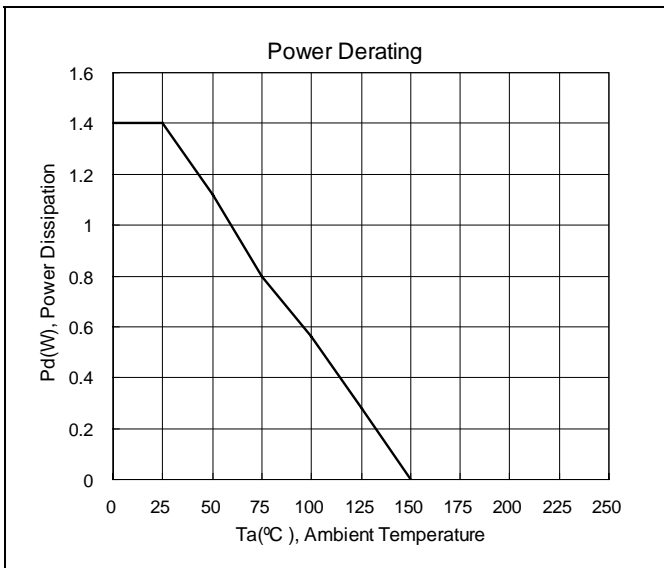
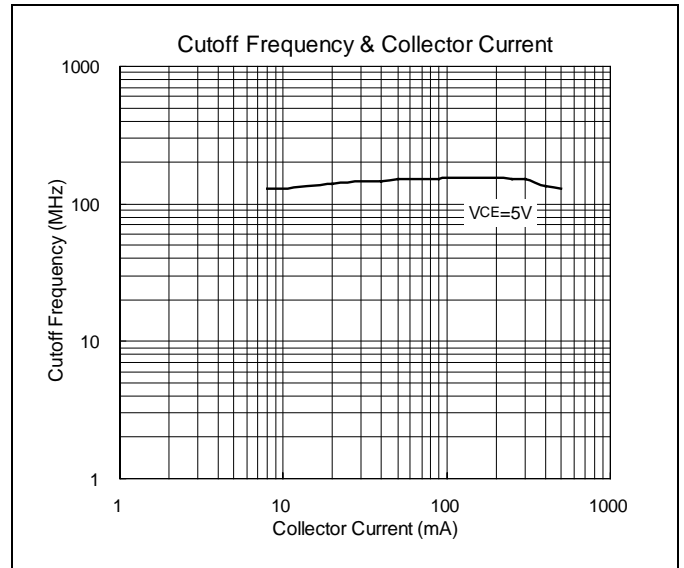
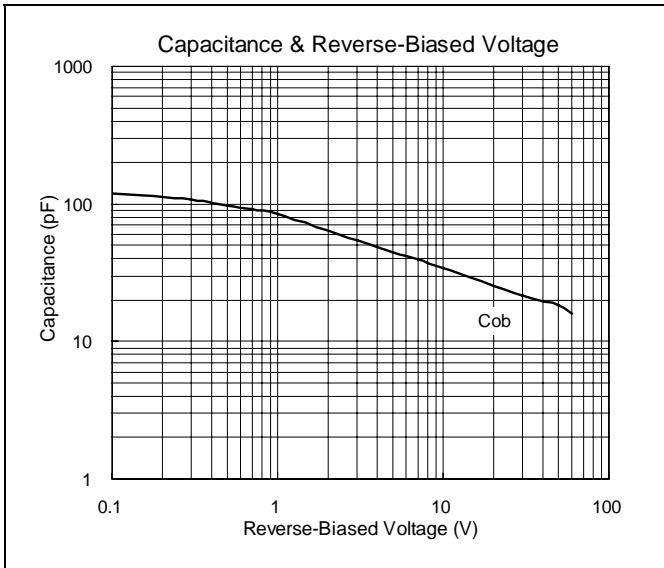
## Classification Of hFE1

Rank	Q	P	E
Range	100-200	160-320	250-500



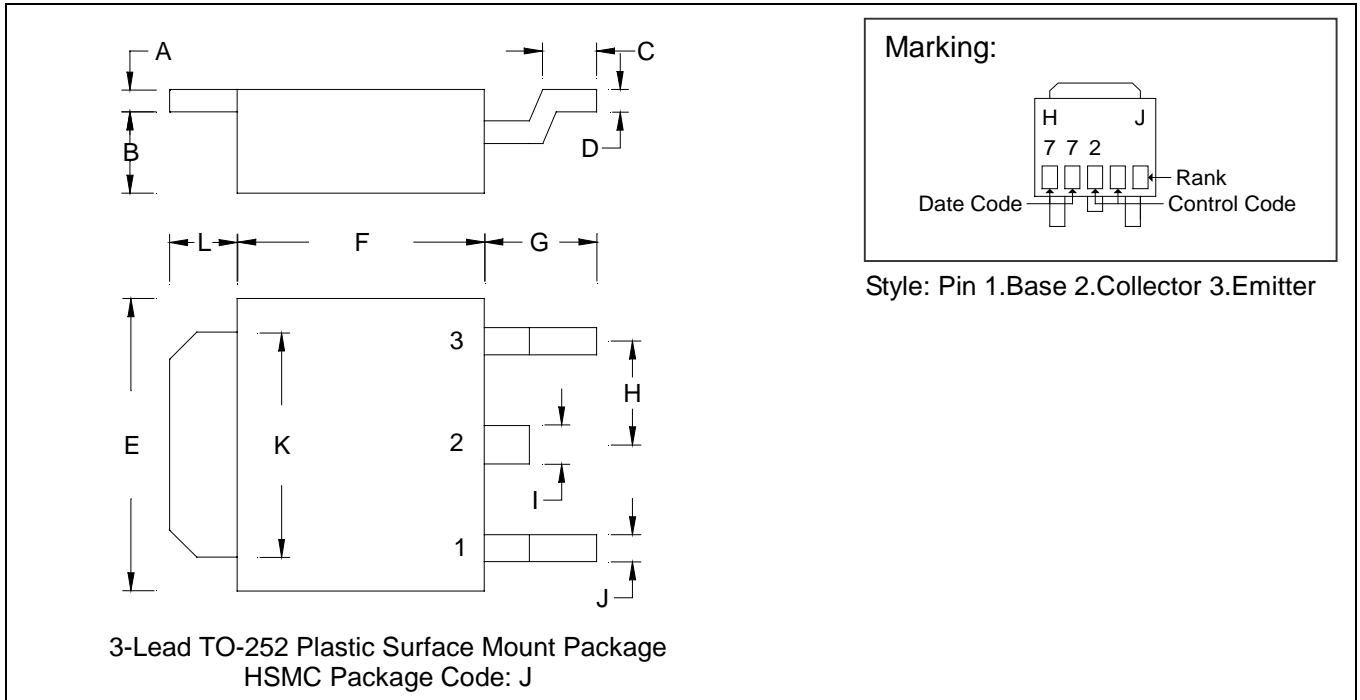
### Characteristics Curve







### TO-252 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

- Notes:
- 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
  - 2.Controlling dimension: millimeters.
  - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

**Important Notice:**

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

**Head Office And Factory:**

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.  
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
 Tel: 886-3-5983621~5 Fax: 886-3-5982931

This datasheet has been download from:

[www.datasheetcatalog.com](http://www.datasheetcatalog.com)

Datasheets for electronics components.